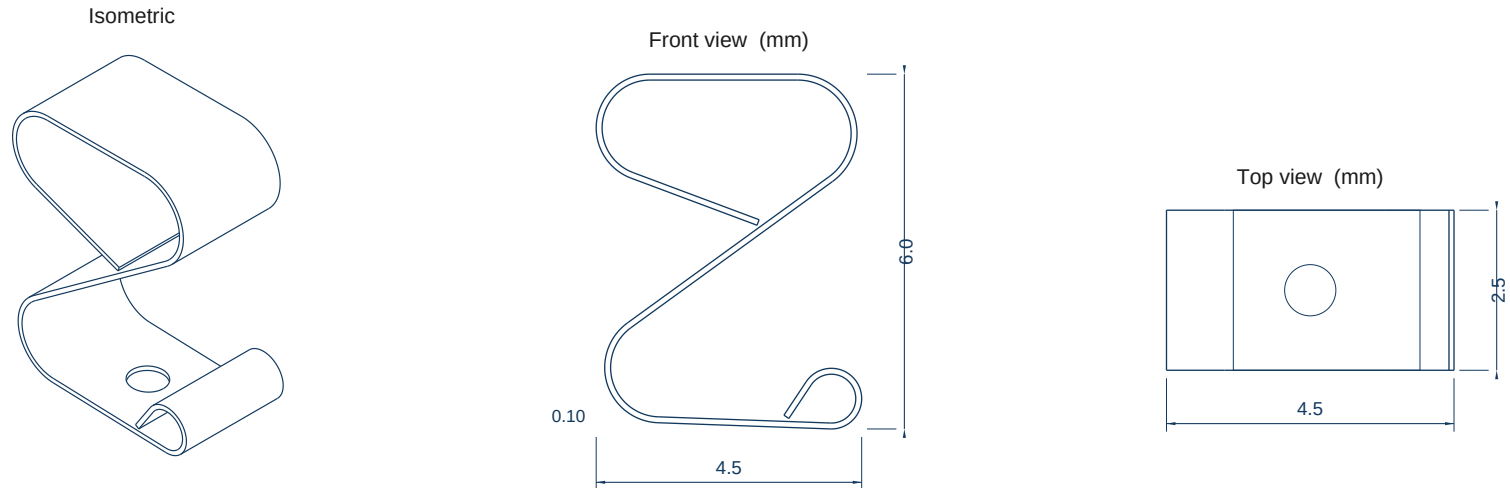




Type 5-04 B504-25045060

SMD EMI Spring Contact | Beryllium Copper | Units: mm



MECHANICAL

VALUE

Thickness	0.10 mm
Width	2.5 mm +/- 0.2
Length	4.5 mm +/- 0.2
Height	6.0 mm +/- 0.2
Form	Z-form: closed top loop, diagonal web, base plate + end hook
Top curls	R0.858 / R0.953 CL, 159 / 144 deg (drawing calls R1)
Base curl / hook	R0.883 CL, 142 deg / R0.463 CL, 238 deg
Diagonal web	4.21 mm at 36 deg to the plates
Free ends	top-loop tongue 2.27 mm / hook tip 0.68 mm
Base hole	dia 0.80 mm, centred (2.25 / 1.25)
Developed length	21.48 mm
Material / plating	BeCu, Gold-plated (G)
Volume / mass	5.320 mm ³ 44.5 mg (BeCu)

PRODUCT DATA

VALUE

Mfr P/N	B504-25045060G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 4.5x2.5x6.0mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-5-04.html
File format	STEP AP214